

■ **PRODUCT CHARACTERISTICS**

VDSS	20V
$R_{DS(on)}$ Typ( $V_{GS}@=4.5V$ )	5.2mΩ
$R_{DS(on)}$ Typ( $V_{GS}@=2.5V$ )	6.8mΩ
ID	55A

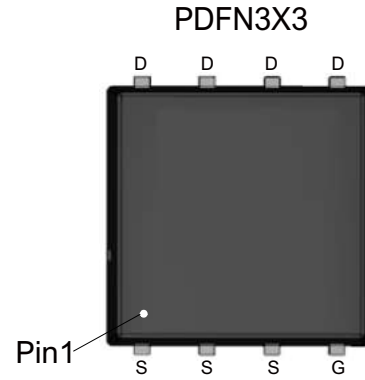
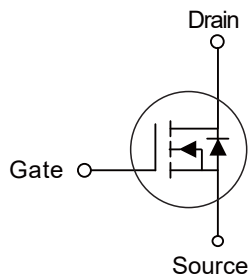
■ **FEATURES**

- Low reverse transfer capacitance
- Fast switching capability

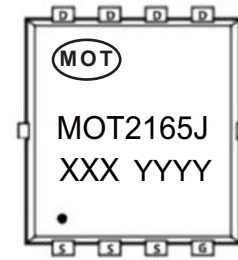
■ **APPLICATIONS**

- Power switching application
- Notebook Vcore

■ **SYMBOL**



Pin configuration (Top view)



XXX = Lot Number  
YYYY = Year Week

**Marking**

**Order information**

Device	Package	Shipping
MOT2165J/TR	PDFN3X3	5000Tape&Reel

**■ ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C unless otherwise noted)**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current	I <sub>D</sub> <sup>①</sup>	55	A
Pulsed Drain Current	I <sub>DM</sub> <sup>②</sup>	200	A
Single Pulsed Avalanche Energy	E <sub>AS</sub> <sup>③</sup>	80	mJ
Maximum Power Dissipation	P <sub>D</sub> <sup>①</sup>	30	W
Thermal Resistance from Junction to Ambient	R <sub>θJA</sub>	40	°C/W
Thermal Resistance from Junction to Case	R <sub>θJC</sub>	4.5	°C/W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

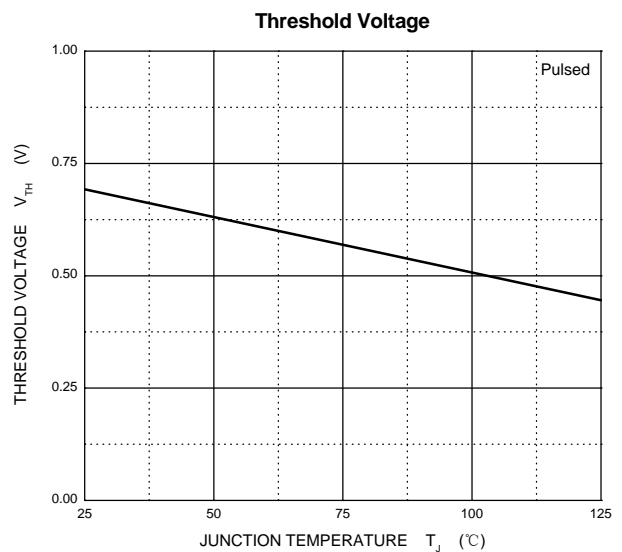
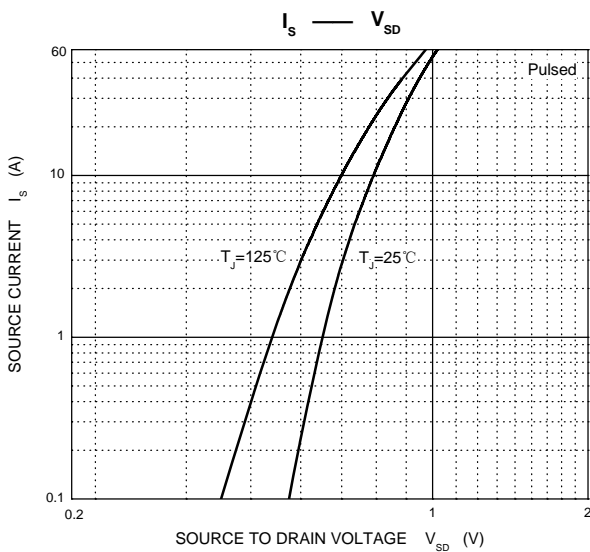
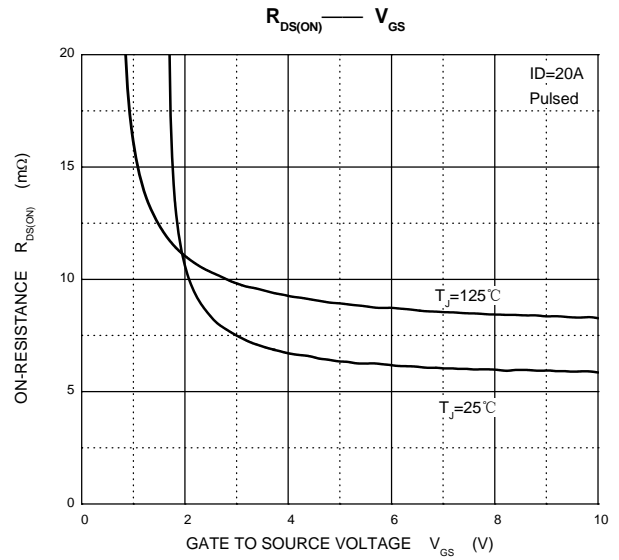
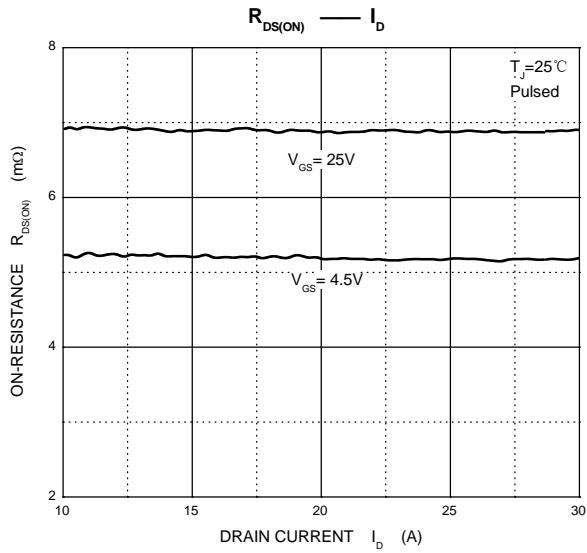
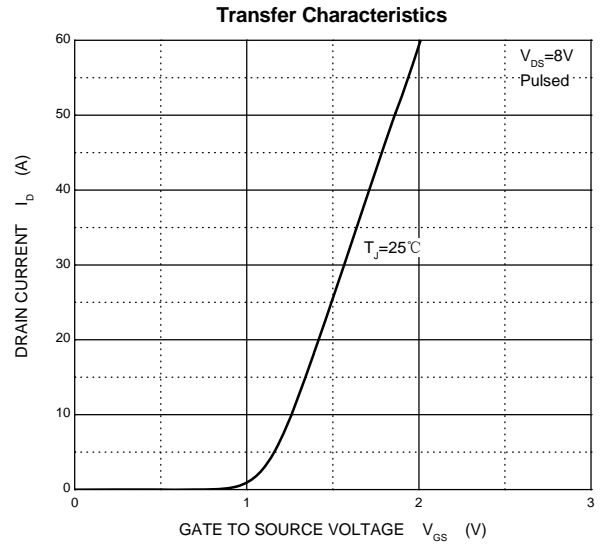
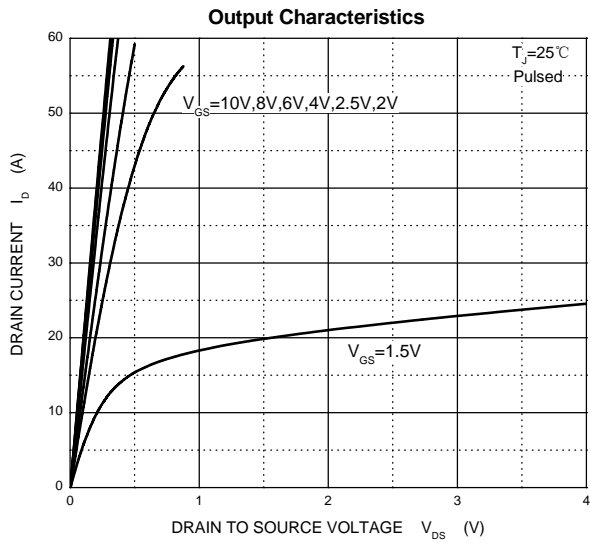
**■ ELECTRICAL CHARACTERISTICS (T<sub>C</sub>=25°C, unless otherwise specified)**

Parameter	Symbol	Test condition	Min	Typ	Max	Unit
<b>Off characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 16V, T <sub>J</sub> = 25°C	-	-	1.0	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±12V	-	-	±100	nA
<b>On characteristics<sup>④</sup></b>						
Gate-threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.4	0.7	1.2	V
Static drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	5.2	6.5	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 20A	-	6.8	8.5	mΩ
Forward transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 20A	-	24	-	S
<b>Dynamic characteristics<sup>④⑤</sup></b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 100KHz	-	1145	-	pF
Output capacitance	C <sub>oss</sub>		-	189	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	181	-	
Gate resistance	R <sub>g</sub>	f = 1MHz	-	3.9	-	Ω
<b>Switching characteristics</b>						
Total gate charge	Q <sub>g</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 25V, I <sub>D</sub> = 14A	-	35	-	nC
Gate-source charge	Q <sub>gs</sub>		-	1.0	-	
Gate-drain charge	Q <sub>gd</sub>		-	8.3	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 14A, R <sub>G</sub> = 3Ω, R <sub>L</sub> = 0.75Ω,	-	10	-	ns
Turn-on rise time	t <sub>r</sub>		-	34	-	
Turn-off delay time	t <sub>d(off)</sub>		-	41	-	
Turn-off fall time	t <sub>f</sub>		-	11	-	
<b>Drain-source diode characteristics</b>						
Drain-source diode forward voltage	V <sub>SD</sub> <sup>④</sup>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A	-	-	1.2	V
Drain-source diode forward current	I <sub>S</sub> <sup>①</sup>		-	-	55	A
Pulsed drain-source diode forward current	I <sub>SM</sub> <sup>②</sup>		-	-	200	A

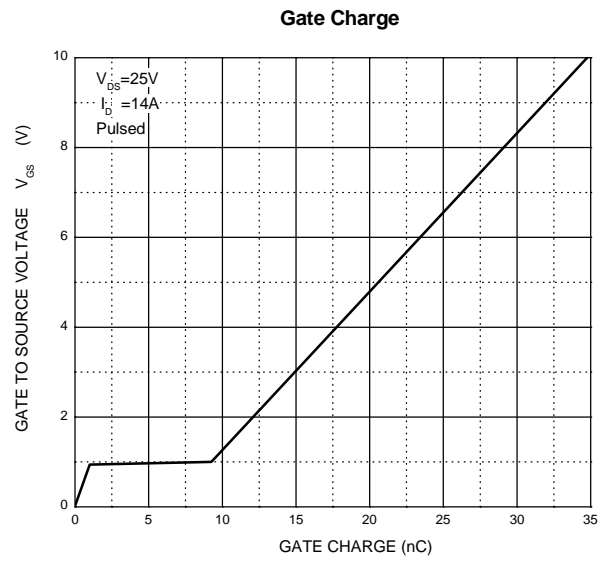
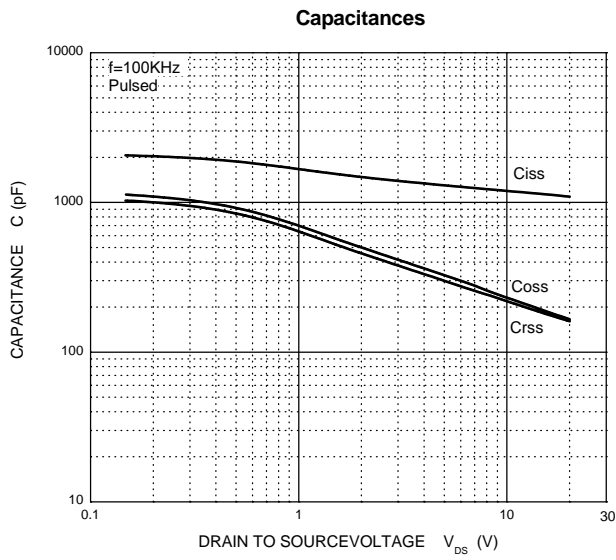
Notes:

1. T<sub>C</sub> = 25°C Limited only by maximum temperature allowed.
2. P<sub>W</sub> ≤ 10μs, Duty cycle ≤ 1%.
3. EAS condition: V<sub>DD</sub> = 10V, V<sub>GS</sub> = 10V, L = 0.5mH, R<sub>G</sub> = 25Ω Starting T<sub>J</sub> = 25°C.
4. Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
5. Guaranteed by design, not subject to production.

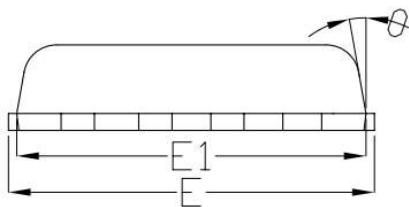
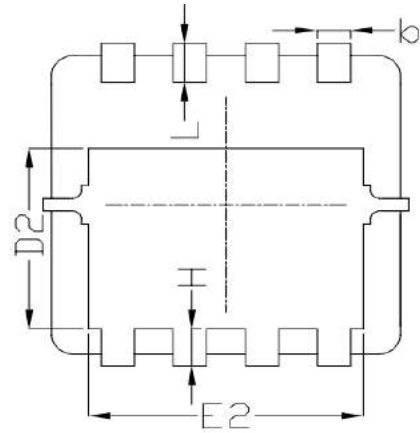
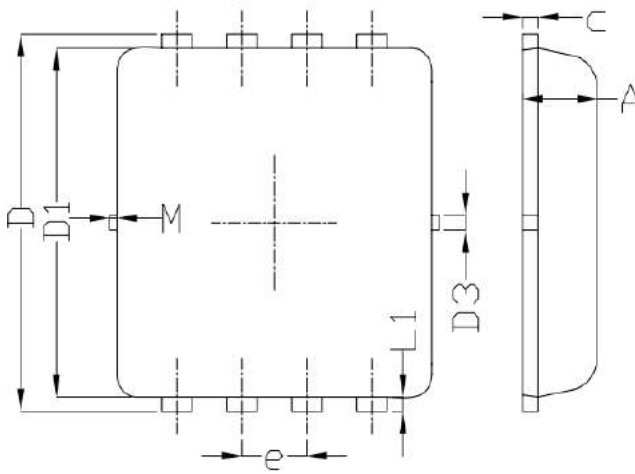
■ TYPICAL CHARACTERISTICS



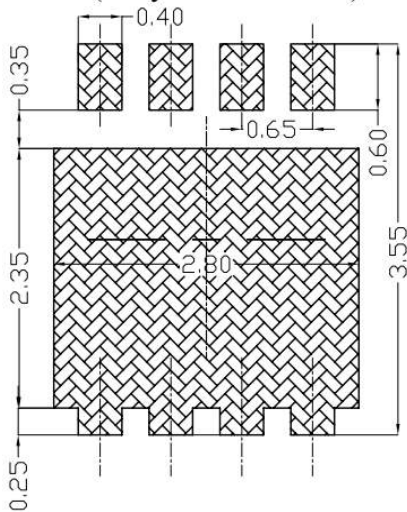
■ TYPICAL CHARACTERISTICS(Cont.)



■ PDFN3X3 PACKAGE OUTLINE DIMENSIONS



Land Pattern  
(Only for Reference)



SYMBOL	DIMENSIONAL REOMTS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	---	0.13	---
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	---	0.13	---
$\theta$	---	10°	12°
M	*	*	0.15
* Not specified			

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